

微細尺寸點錫用錫膏

Solder Paste for Fine Dispensing

- 高熔點 Sn-10Sb : 245-266 °C
- 標準 Sn-3.0Ag-0.5Cu : 217-220 °C
- 低熔點 Sn-58Bi : 139 °C

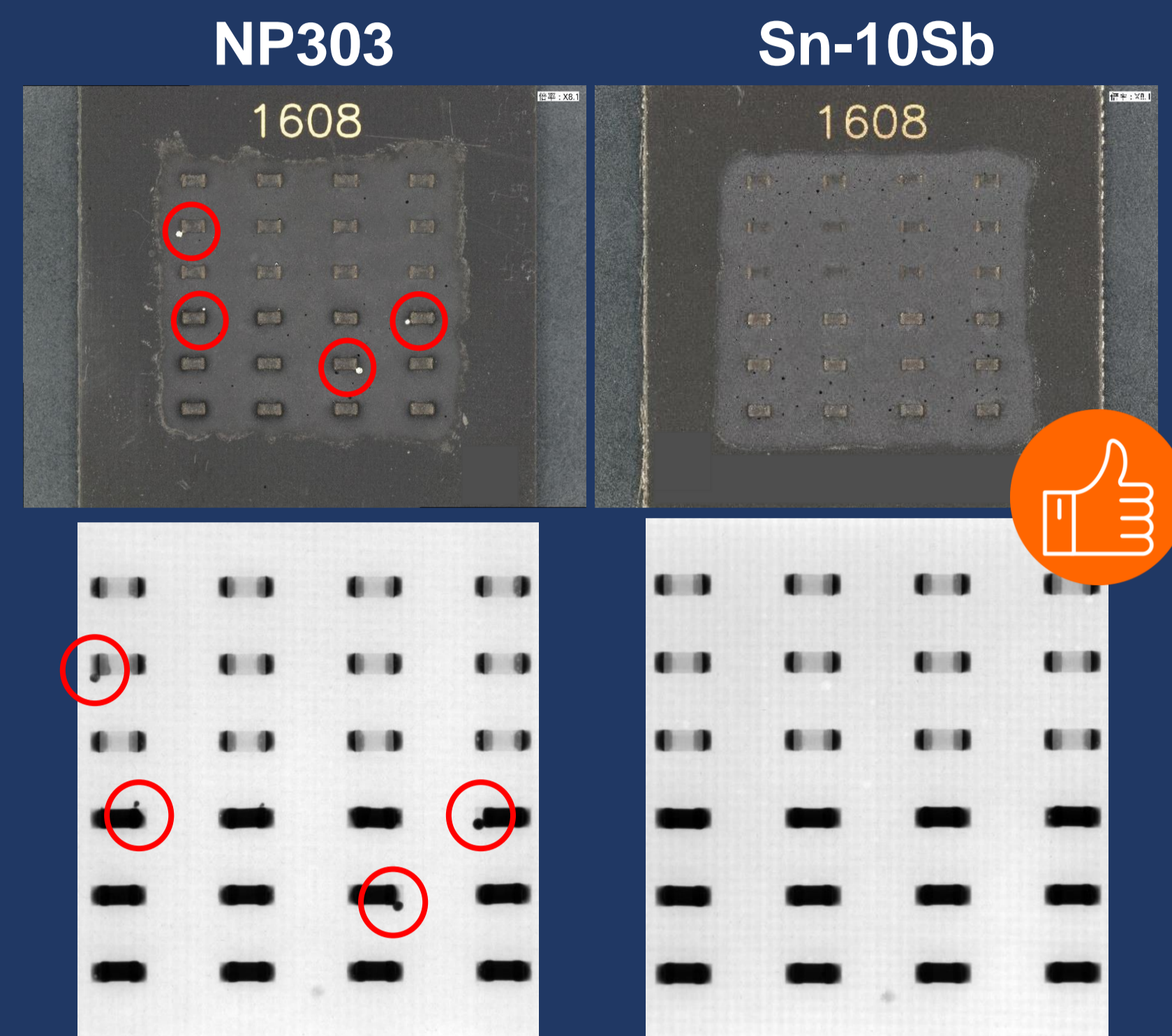
- Type 5, 6, 7

- 免洗型
- 水洗型

- Jet Dispense
- Air Dispense

高熔點 系列

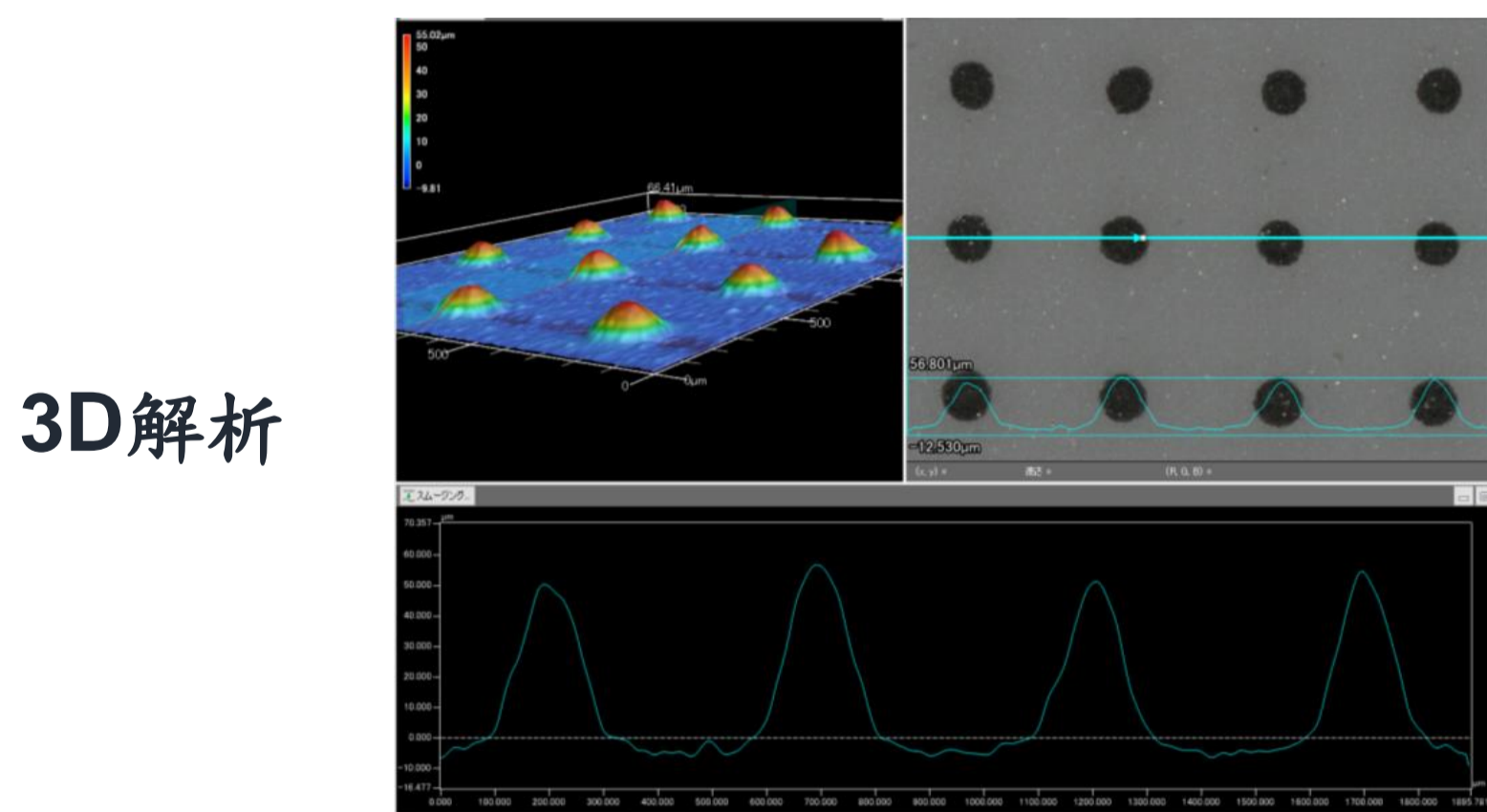
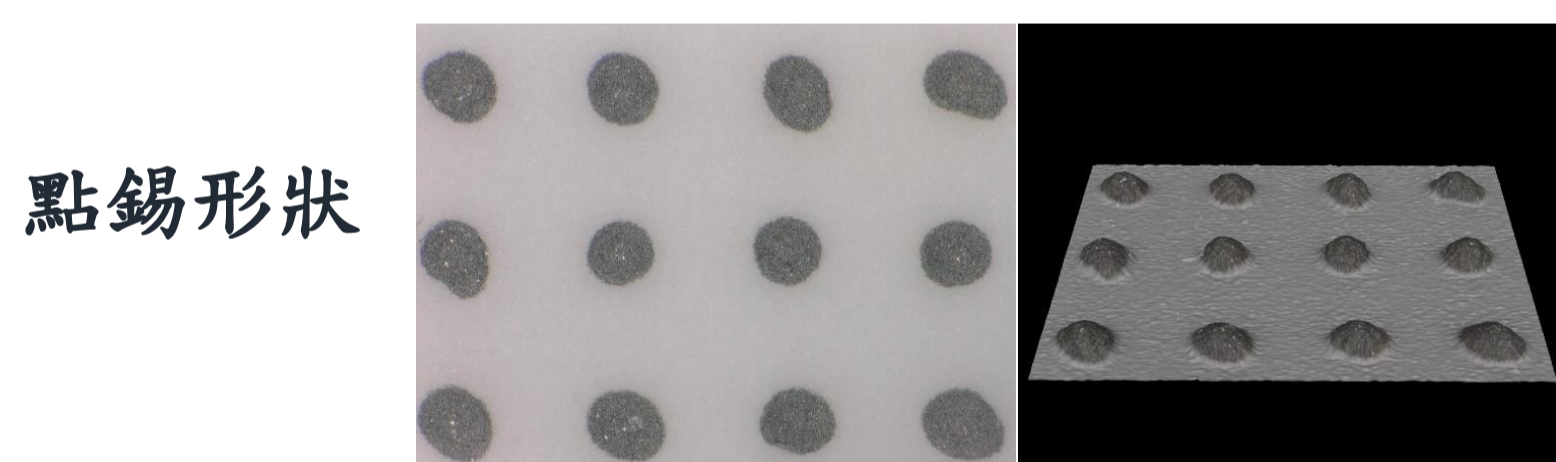
即使有二次封裝製程也不用擔心！
實驗溫度：245°C



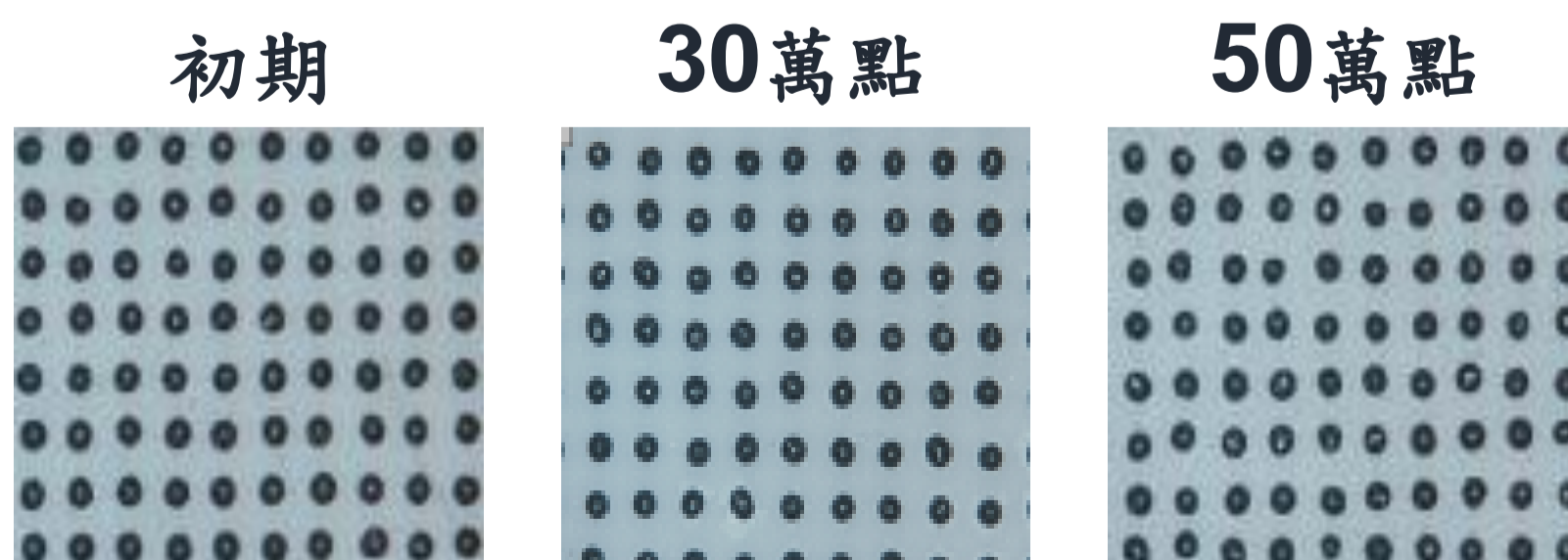
使用高熔點錫膏，在二次加熱時也不易熔融

Jet Dispense 系列

專為Jet Dispense產品設計的 **winDot** 錫膏
可點出Φ200 μm以下尺寸！



連續穩定點錫



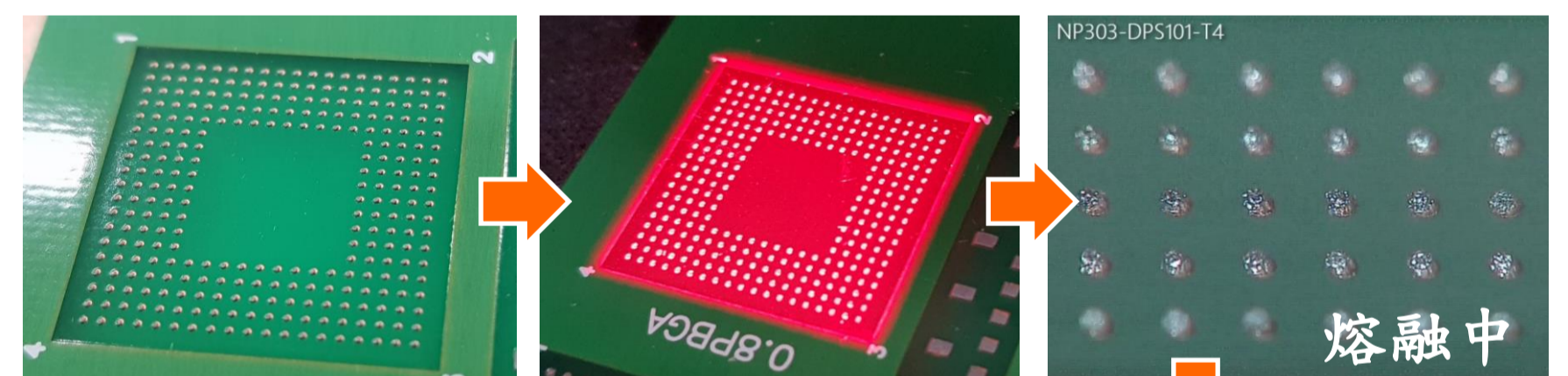
winDot-F005-NP303

Air Dispense 系列

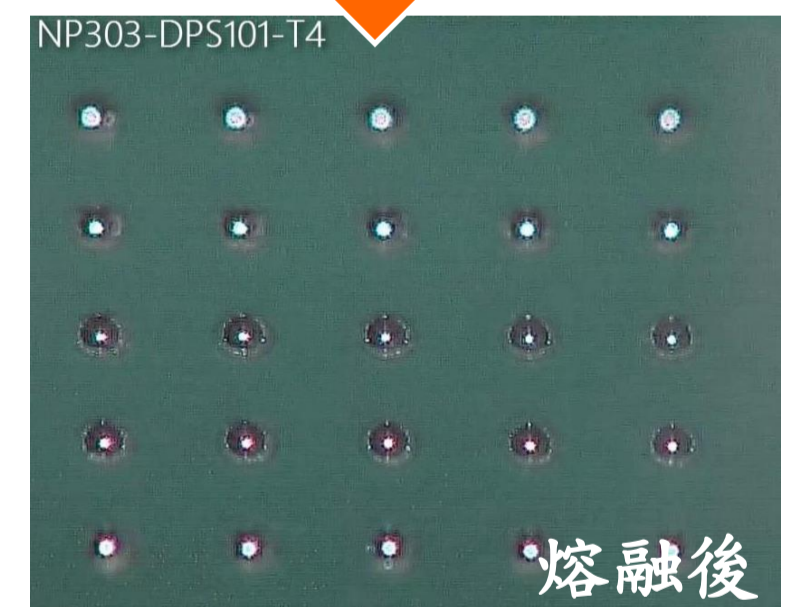
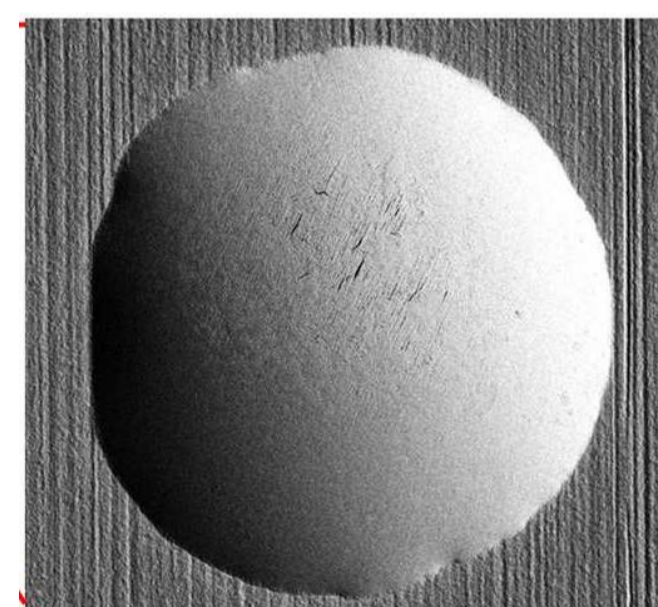
錫膏熔融時間一致，且加熱後熔融均勻

Area Laser Soldering

NP303-DPS101-T4

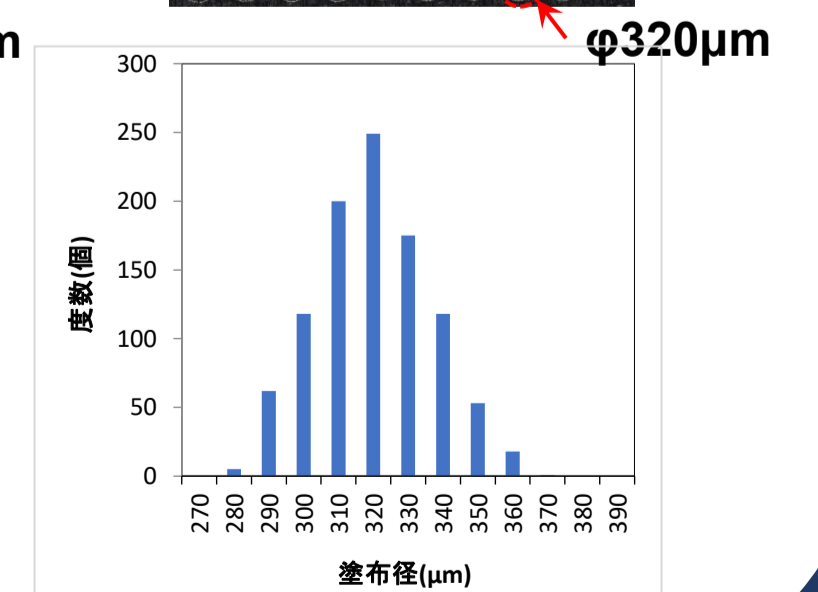
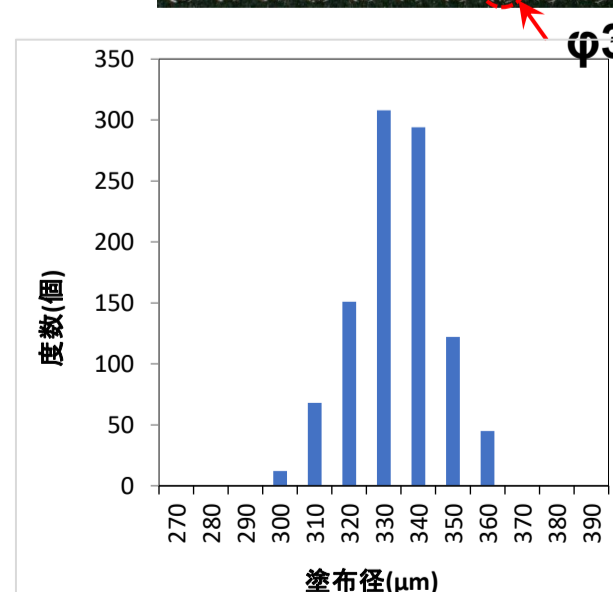
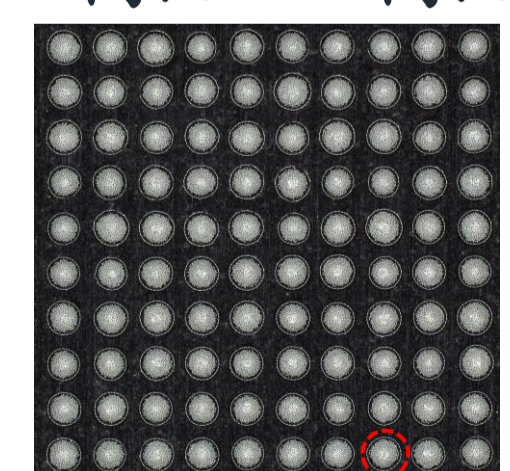
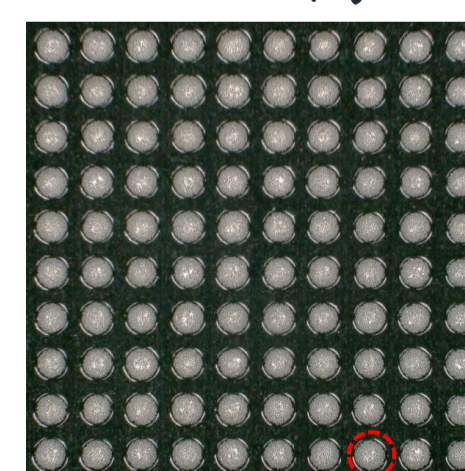


良好的洗淨性



1點-10萬點

36萬點-37萬點



連續穩定點錫

